

COMPSAC 2016 Symposium on Technologies and Applications of the Internet (TAIN)

Message from the Program Co-chairs

It is our pleasure to welcome you to COMPSAC 2016 Symposium on Technologies and Applications of the Internet (TAIN). Our Symposium provides a forum to share latest innovations on Internet technologies and applications, which perfectly matches with the main theme of COMPSAC this year. Topics of interest for TAIN include all types of networks with their architectures and applications as well as their management, performance, and security. Moreover, TAIN addresses Internet of things (IoT), machine-to-machine (M2M) and peer-to-peer (P2P) communications, content distribution networks (CDN) and also emerging network technologies such as software defined networks (SDN). A vast array of challenges for Internet technologies and applications and proposals for solutions will be discussed in TAIN Symposium.

This year, TAIN received 15 full submissions. Each submission underwent a rigorous double-blind review process and was discussed by the program committee during the PC meeting, which took place in Tokyo, Japan, in February 2016. As the result of this process, we accepted two submissions as regular papers and three submissions as short papers for inclusion into this year's COMPSAC proceedings as TAIN Symposium papers, published by IEEE CS. All accepted papers will be presented in the conference. We would like to take this opportunity to thank the authors, who submitted their valuable research results and the members of the TAIN Program Committee and external reviewers, who contributed to the success of the program assembled for TAIN 2016.

We would like to express our gratitude to Sorel Reisman (Standing Committee Chair of COMPSAC), Sheikh Iqbal Ahamed (Steering Committee Chair) as well as Ling Liu and Dejan Milojicic (General Chairs) for their ongoing support and contributions. In particular, we thank William Claycomb, Mihhail Matskin, Hiroyuki Sato (Program Chairs-in-Chief) for their coordination and putting everything together for a great conference. Our thanks will also be for all the chairs and the organizing committee for their hard work.

We hope that you will find the symposium both valuable and productive.

TAIN Program Co-Chairs

Tugkan Tuglular, *Izmir Institute of Technology, Turkey*

Ying Cai, *Iowa State University, USA*

TAIN General Chair

Schahram Dustdar, *Vienna University of Technology, Austria*

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Katsuyuki Yamazaki, *Nagaoka University of Technology, Japan*